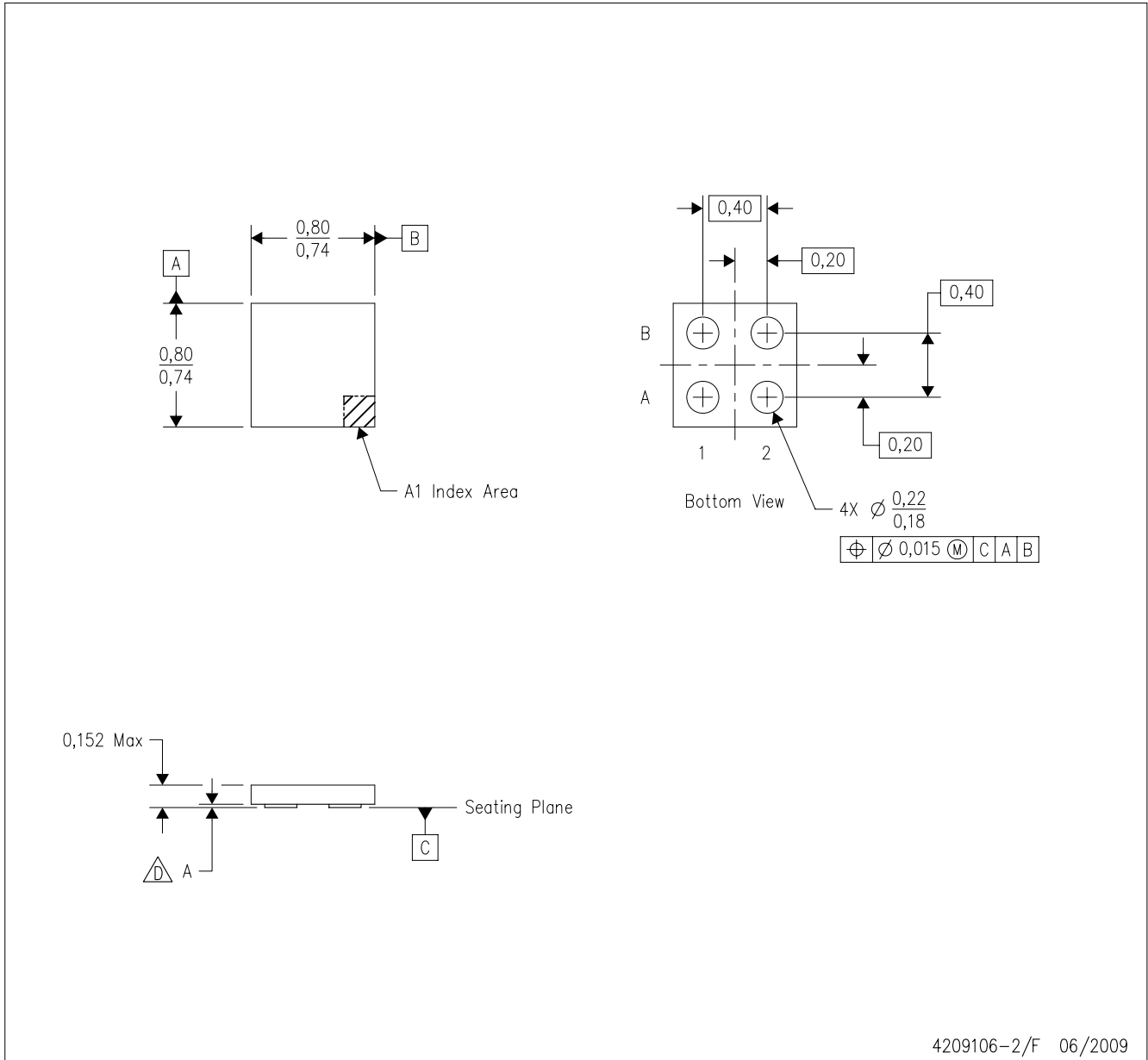


YFM (S-XLGA-N4)

DIE-SIZE LAND GRID ARRAY



4209106-2/F 06/2009

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. PicoStar™ package configuration.
 - ⚠ Devices in this YFM package can have dimension A ranging from 0.0048 to 0.0120 mm. If the land plating is copper, the range is 0.0048 to 0.0072 mm. If the land plating is CuNiPd, the range is 0.0070 to 0.0120 mm. To determine the exact land plating of a specific device, refer to the device datasheet or contact a local TI representative.
 - E. This package is a Pb-free solder land design.

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